



-50A, -60V P-CHANNEL POWER MOSFET

Description

This model is an advanced trench MOSFET with better characteristics, such as fast switching time, low gate charge and low on state resistance.

Such enhanced MOSFET are commonly used in switching power supplies and adapters for high-speed switching applications.

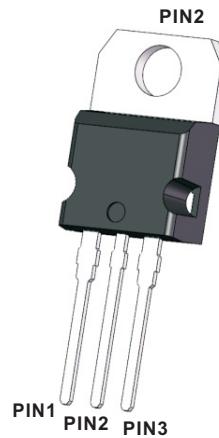
Features

- $R_{DS(ON)} < 22m\Omega$ @ $V_{GS}=-10V$, $I_D=-25A$
- Extremely low on impedance
- Low gate charge
- Superior switching characteristics

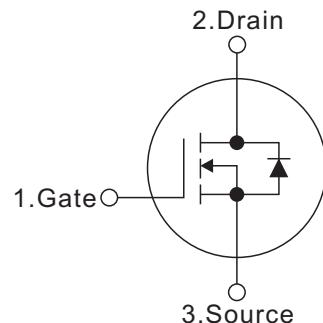
Mechanical data

- Case: TO-220-3L
- Approx. Weight: 2.04g (0.072oz)
- RoHS compliant
- Case Material: "Green" molding compound, UL flammability classification 94V-0, "Halogen-free".

TO-220-3L(*Prefix :C)



✓
RoHS
COMPLIANT



Absolute Maximum Ratings (Ta=25°C, Unless Otherwise Specified)

Parameter	Symbols	Ratings	Units
Drain-Source Voltage	V_{DSS}	-60	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current <small>Tc=25°C Tc=100°C</small>	I_D	-50 -35.4	A
Pulsed Drain Current (Note 2)	I_{DM}	-200	A
Avalanche Energy Single Pulsed (Note 3)	E_{AS}	490	mJ
Power Dissipation	P_D	115	W
Operating junction and storage temperature	T_J, T_{STG}	-55 ~ +150	°C

Notes:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.
2. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
3. Repetitive Rating: Pulse width limited by maximum junction temperature.

L = 0.5mH, IAS=10A, VDD = 50V, RG = 25 Ω, Starting TJ = 25°C

Thermal Resistance

Parameter	Symbols	Ratings	Units
Thermal resistance, junction – case.	R_{thJC}	1.08	°C/W
Thermal resistance, junction – ambient(min. footprint)	R_{thJA}	62	°C/W



Electrical Characteristics (Ta=25°C, Unless Otherwise Specified)

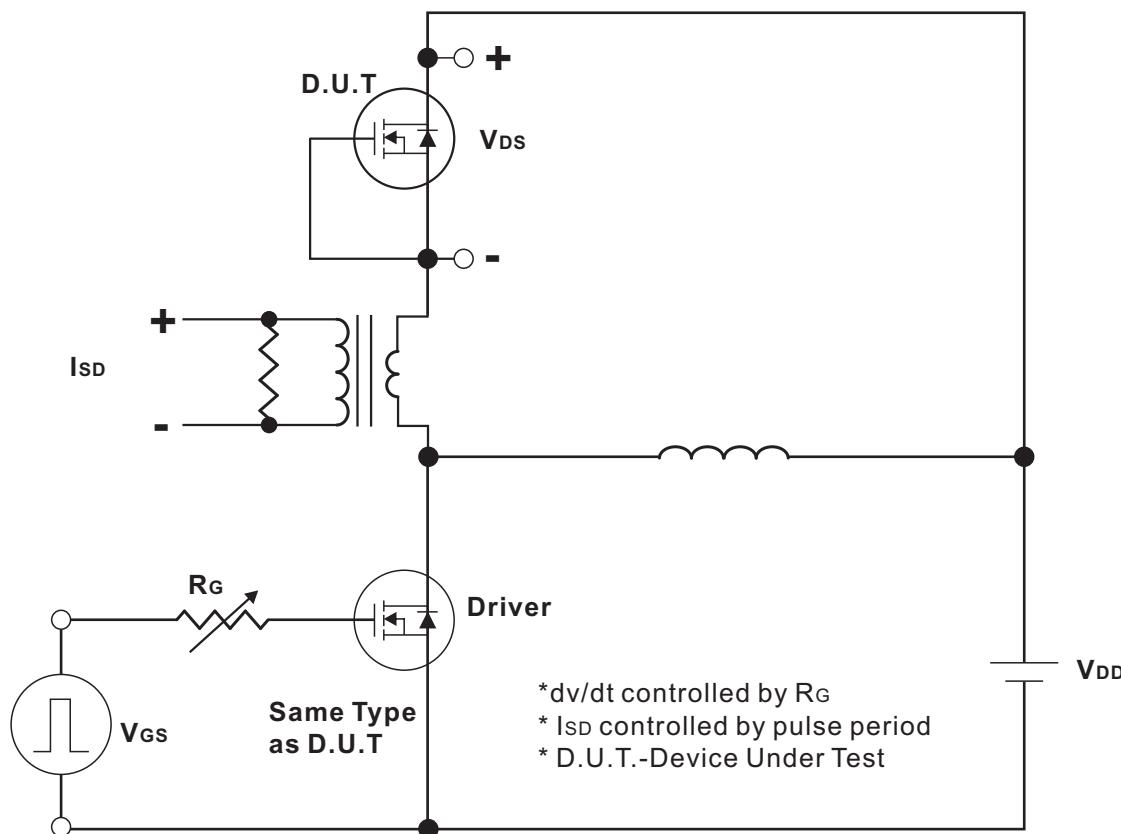
Parameter	Symbols	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{DS}=0V, I_D=-250\mu A$	-60			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=-60V, V_{GS}=0V$			1	μA
Gate- Source Leakage Current	Forward	$V_{GS}=-20V, V_{DS}=0V$			100	nA
	Reverse	$V_{GS}=-20V, V_{DS}=0V$			-100	
On Characteristics						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.0		-3.0	V
Static Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-25A$ $V_{GS}=-4.5V, I_D=-10A$	18 20	22 26		$m\Omega$
Transconductance	g_{fs}	$V_{DS}=5V, I_D=10A$		10		S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=-25V,$ $V_{GS}=0V,$ $f=1.0MHz$		1050		pF
Output Capacitance	C_{oss}			460		pF
Reverse Transfer Capacitance	C_{rss}			70		pF
Gate resistance	R_G			4		Ω
Switching Characteristics						
Total Gate Charge (Note 1)	Q_G	$V_{DS}=-48V, V_{GS}=-10V,$ $I_D=-50A$ (NOTE1,2)		32		nC
Gate-Source Charge	Q_{GS}			8		nC
Gate-Drain Charge	Q_{GD}			12		nC
Turn-On Delay Time (Note 1)	$t_{D(ON)}$	$V_{DS}=-30V, V_{GS}=-10V,$ $I_D=-25A, R_G=25\Omega$ (NOTE1,2)		20		ns
Turn-On Rise Time	t_R			100		ns
Turn-Off Delay Time	$t_{D(OFF)}$			80		ns
Turn-Off Fall Time	t_F			85		ns
Drain-Source Diode Characteristics And Maximum Ratings						
Maximum Body-Diode Continuous Current	I_S				-50	A
Drain-Source Diode Forward Voltage (Note 1)	V_{SD}	$I_S=-50A, V_{GS}=0V$			-1.5	V
Reverse Recovery Time (Note 1)	trr	$I_S=-50A, V_{GS}=0V,$ $di/dt=100A/us$		200		ns
Reverse Recovery Charge	Qrr			135		nC

Notes:

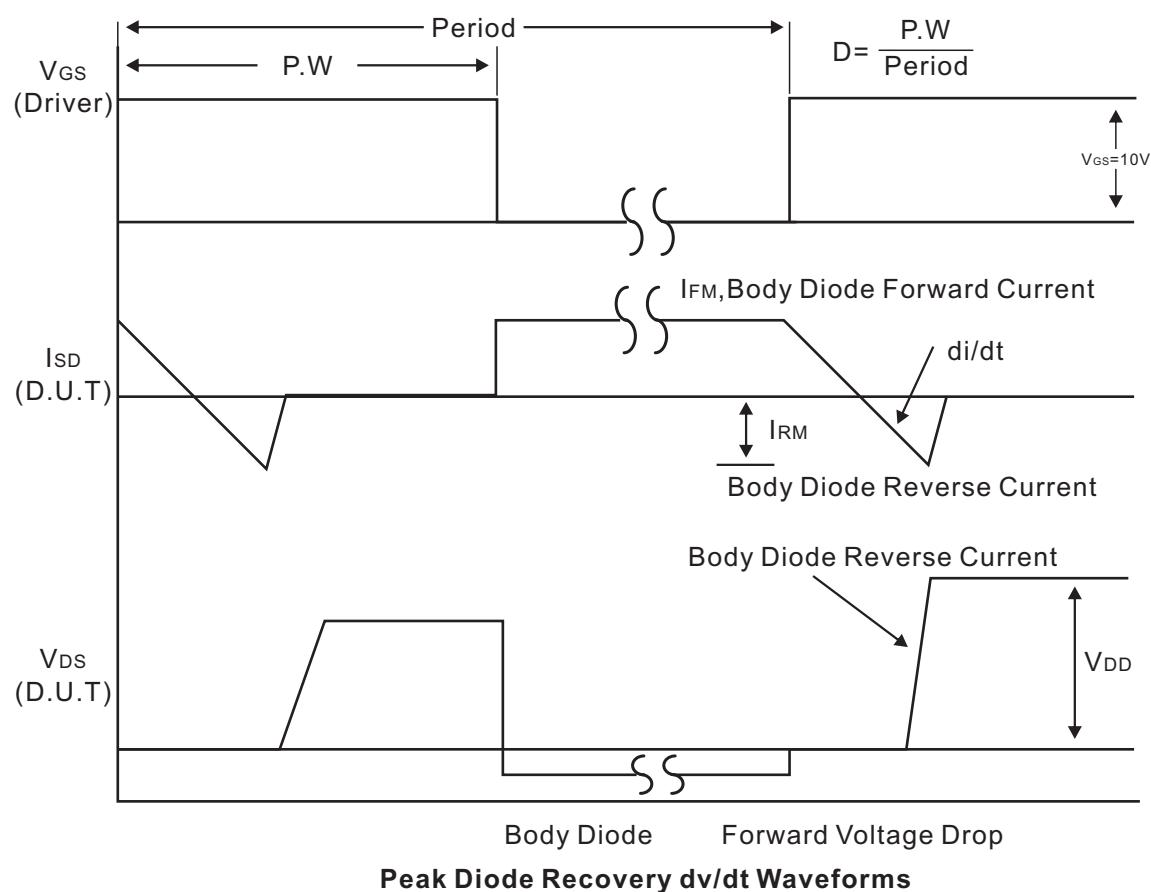
1. Pulse Test: Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$.
2. Essentially independent of operating temperature.



Test Circuits and waveforms

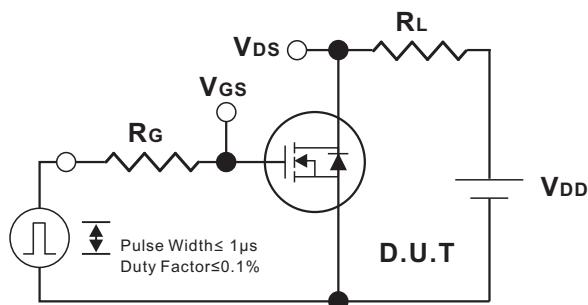


Peak Diode Recovery dv/dt Test Circuit

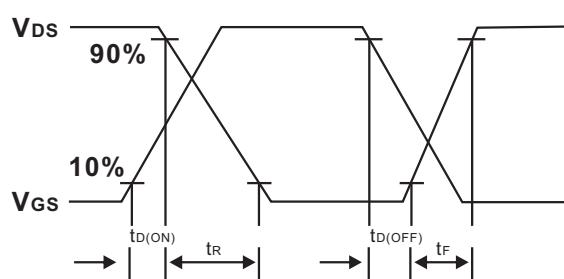




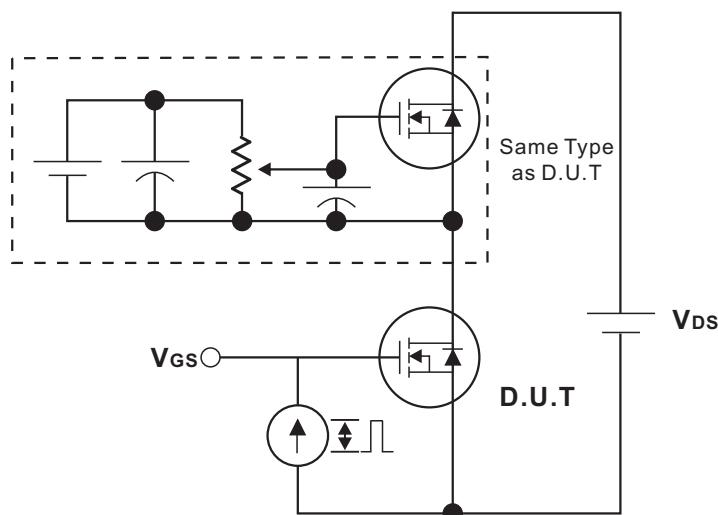
Test Circuits and waveforms



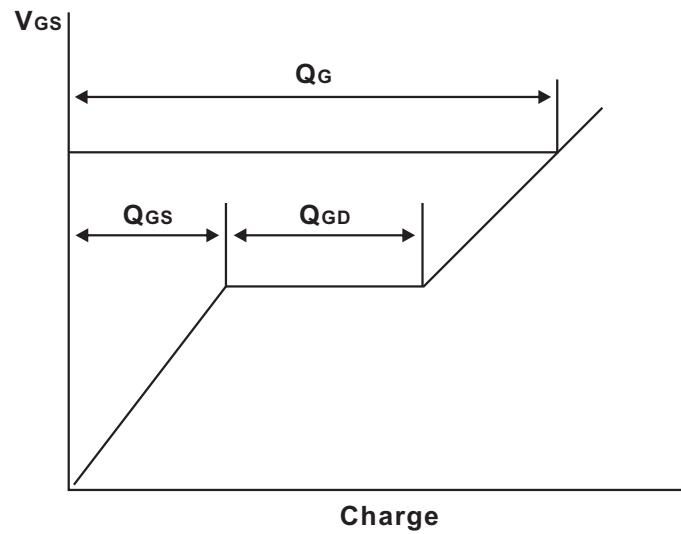
Switching Test Circuit



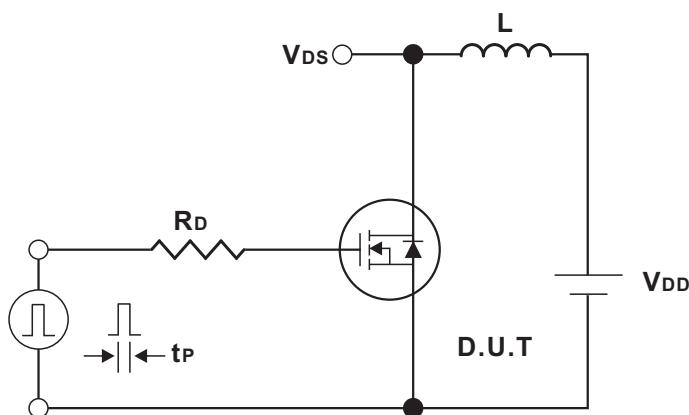
Switching Waveforms



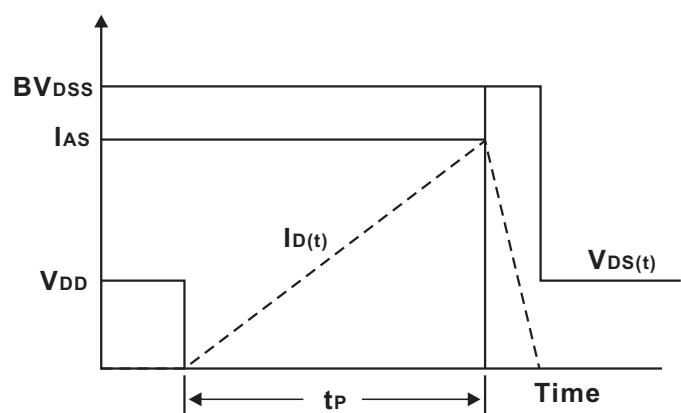
Gate Charge Test Circuit



Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms



Typical Characteristics

Fig.1 Output Characteristics

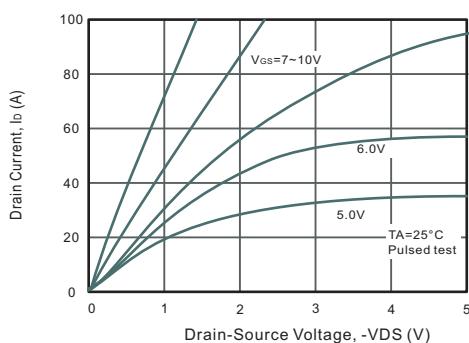


Fig.2 Power Dissipation

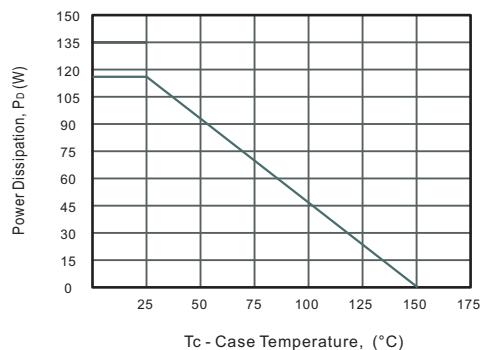


Fig.3 Drain Current Derating

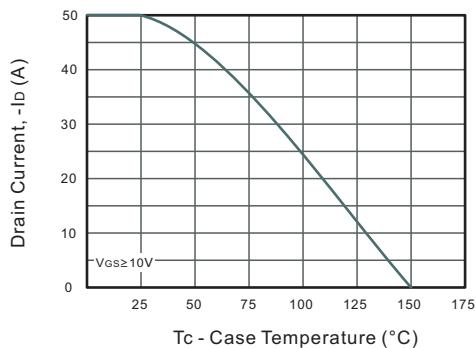


Fig.4 Drain-Source On-Resistance vs. Drain Current

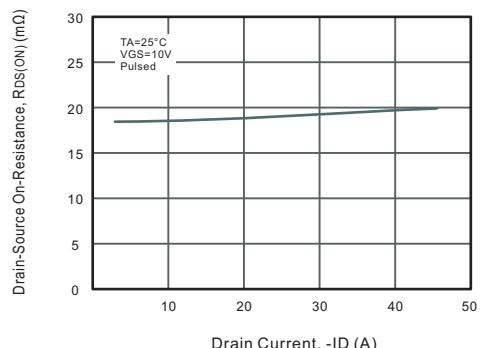


Fig.5 Gate Threshold Voltage vs. Junction Temperature

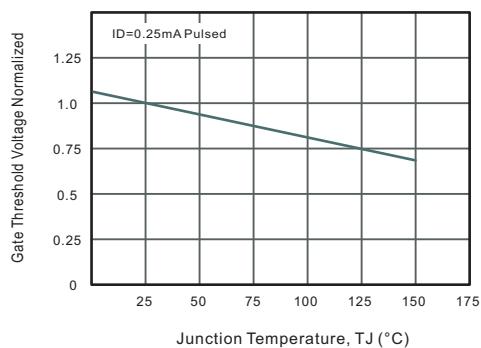


Fig.6 Body-diode Forward Characteristics

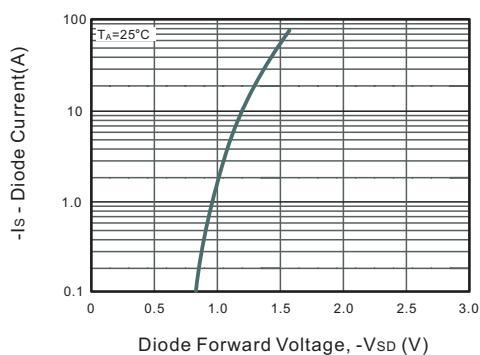


Fig.7 Drain-Source On-Resistance vs. Junction Temperature

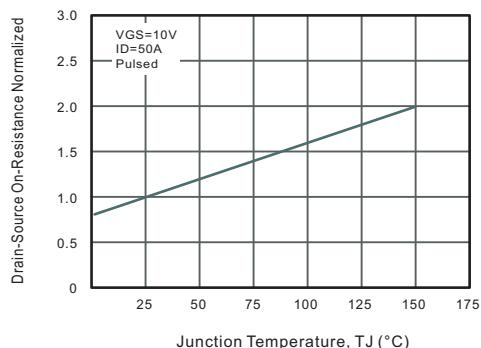
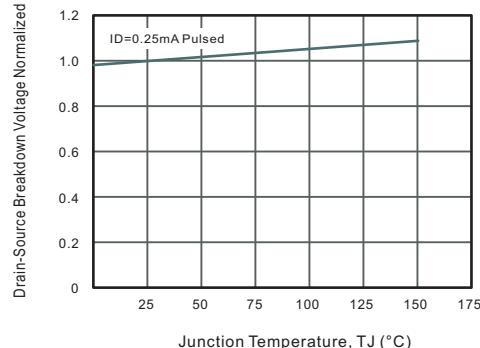


Fig.8 Breakdown Voltage vs. Junction Temperature





Typical Characteristics

Fig.9 Capacitance Characteristics

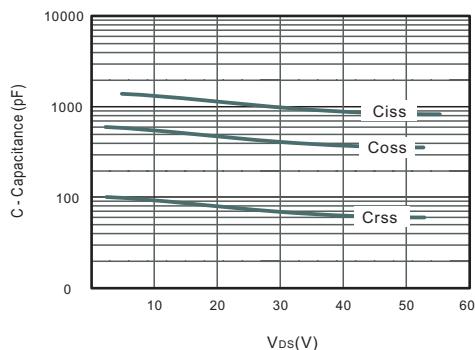


Fig.10 Gate Charge Characteristics

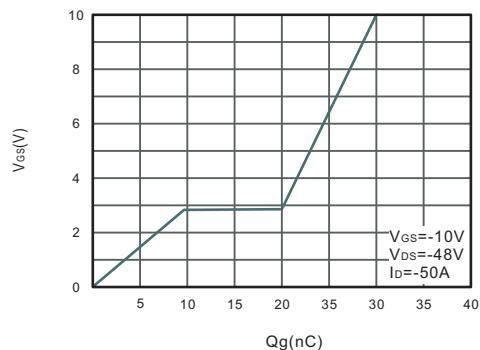


Fig.11 Safe Operating Area

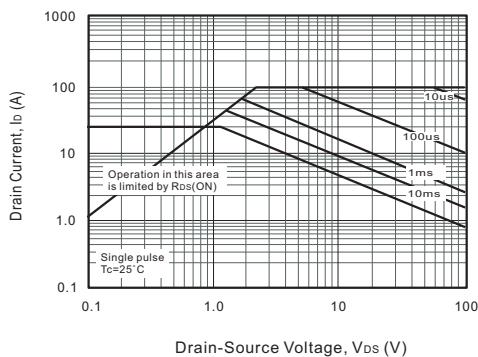
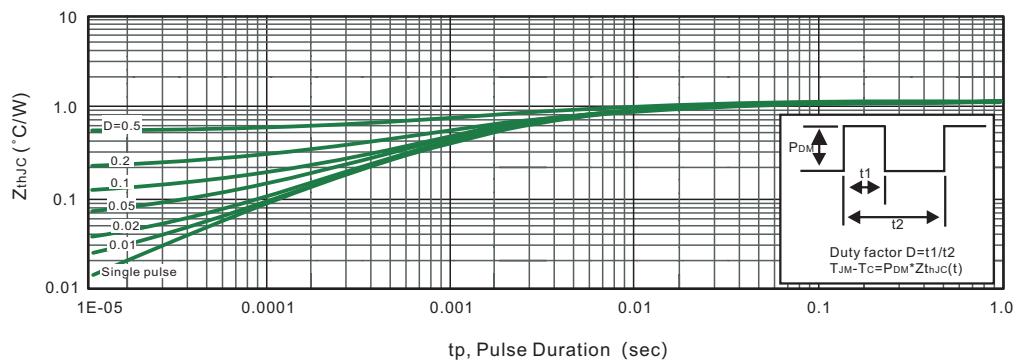


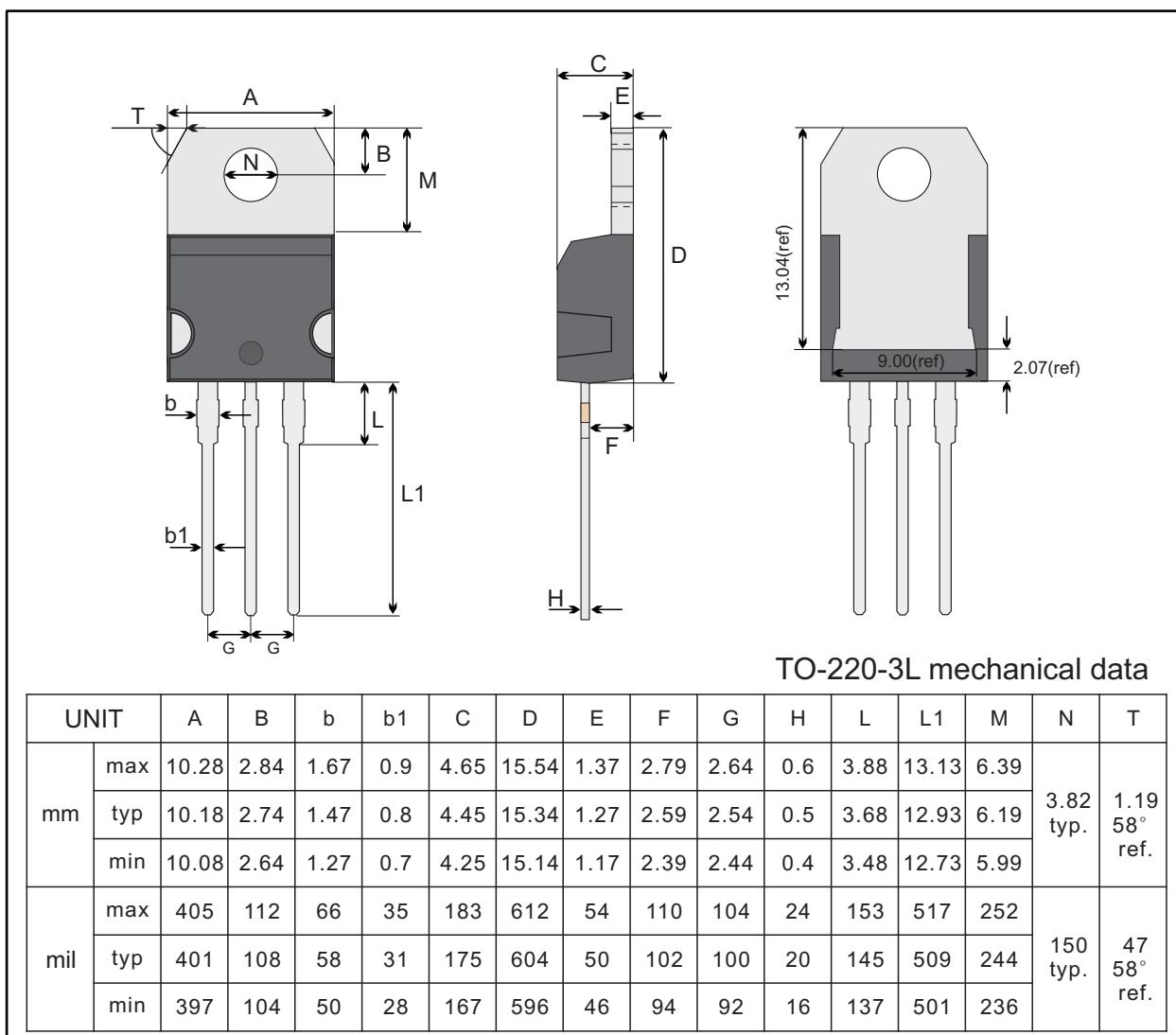
Fig.12 Max. Transient Thermal Impedance





Package Outline
Through Hole Package ; 3 leads

TO-220-3L



TO-220-3L mechanical data

UNIT		A	B	b	b1	C	D	E	F	G	H	L	L1	M	N	T
mm	max	10.28	2.84	1.67	0.9	4.65	15.54	1.37	2.79	2.64	0.6	3.88	13.13	6.39	3.82 typ.	1.19 58° ref.
	typ	10.18	2.74	1.47	0.8	4.45	15.34	1.27	2.59	2.54	0.5	3.68	12.93	6.19		
	min	10.08	2.64	1.27	0.7	4.25	15.14	1.17	2.39	2.44	0.4	3.48	12.73	5.99		
mil	max	405	112	66	35	183	612	54	110	104	24	153	517	252	150 typ.	47 58° ref.
	typ	401	108	58	31	175	604	50	102	100	20	145	509	244		
	min	397	104	50	28	167	596	46	94	92	16	137	501	236		

Marking

Type number	Marking code
C18RP60P	C18RP60P



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